

General Description

The MY75P03NE3 use advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

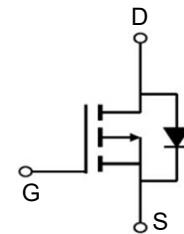
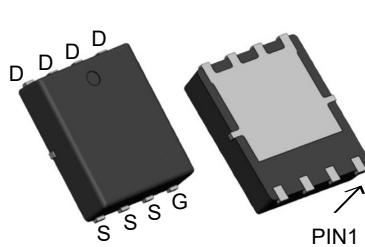


Features

V_{DSS}	-30	V
I_D	-75	A
$R_{DS(ON)}(\text{at } V_{GS} = -10\text{V})$	5.6	$\text{m}\Omega$
$R_{DS(ON)}(\text{at } V_{GS} = -4.5\text{V})$	9.5	$\text{m}\Omega$

Application

- Battery protection
- Load switch
- Uninterruptible power supply



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
MY75P03NE3	PDFN3*3-8	NULL	5000

Absolute Maximum Ratings ($T_c=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-30	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D @ T_c = 25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ -10\text{V}^{1,6}$	-75	A
$I_D @ T_c = 100^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ -10\text{V}^{1,6}$	-55	A
I_{DM}	Pulsed Drain Current ²	-200	A
EAS	Single Pulse Avalanche Energy ³	80	mJ
I_{AS}	Avalanche Current	-40	A
$P_D @ T_c = 25^\circ\text{C}$	Total Power Dissipation ⁴	90	W
T_{STG}	Storage Temperature Range	-55 to 175	$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to 175	$^\circ\text{C}$
$R_{\theta JA}$	Thermal Resistance Junction-ambient ¹ ($t \leq 10\text{S}$)	20	$^\circ\text{C}/\text{W}$
	Thermal Resistance Junction-ambient ¹ (Steady State)	50	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance Junction-case ¹	1.6	$^\circ\text{C}/\text{W}$

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_D=-250\mu\text{A}$	-30	---	---	V
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance ²	$V_{\text{GS}}=-10\text{V}$, $I_D=-20\text{A}$	---	5.6	7.5	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}$, $I_D=-15\text{A}$	---	9.5	13	$\text{m}\Omega$
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_D=-250\mu\text{A}$	-1.2	---	-2.5	V
I_{DSS}	Drain-Source Leakage Current	$V_{\text{DS}}=-24\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	-1	μA
		$V_{\text{DS}}=-24\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=55^\circ\text{C}$	---	---	-5	
I_{CSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
R_g	Gate Resistance	$V_{\text{DS}}=0\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	1.2	---	Ω
Q_g	Total Gate Charge (-10V)	$V_{\text{DS}}=-15\text{V}$, $V_{\text{GS}}=-10\text{V}$, $I_D=-18\text{A}$	---	60	---	nC
Q_{gs}	Gate-Source Charge		---	9	---	
Q_{gd}	Gate-Drain Charge		---	15	---	
$T_{\text{d}(\text{on})}$	Turn-On Delay Time	$V_{\text{DD}}=-15\text{V}$, $V_{\text{GS}}=-10\text{V}$, $R_G=3.3\Omega$, $I_D=-20\text{A}$	---	17	---	ns
T_r	Rise Time		---	40	---	
$T_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	55	---	
T_f	Fall Time		---	13	---	
C_{iss}	Input Capacitance	$V_{\text{DS}}=-25\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	3450	---	pF
C_{oss}	Output Capacitance		---	255	---	
C_{rss}	Reverse Transfer Capacitance		---	140	---	
I_s	Continuous Source Current ^{1,5}	$V_G=V_D=0\text{V}$, Force Current	---	---	-70	A
V_{SD}	Diode Forward Voltage ²	$V_{\text{GS}}=0\text{V}$, $I_s=-1\text{A}$, $T_J=25^\circ\text{C}$	---	---	-1.2	V
t_{rr}	Reverse Recovery Time	$I_F=-20\text{A}$, $\frac{di}{dt}=100\text{A}/\mu\text{s}$, $T_J=25^\circ\text{C}$	---	22	---	nS
Q_{rr}	Reverse Recovery Charge		---	72	---	nC

NOTE :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle 2%
- 3.The EAS data shows Max. rating . The test condition is $V_{\text{DD}}=-50\text{V}$, $V_{\text{GS}}=-10\text{V}$, $L=0.1\text{mH}$, $I_{\text{AS}}=-40\text{A}$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation
- 6.The maximum current rating is package limited.

Typical Characteristics

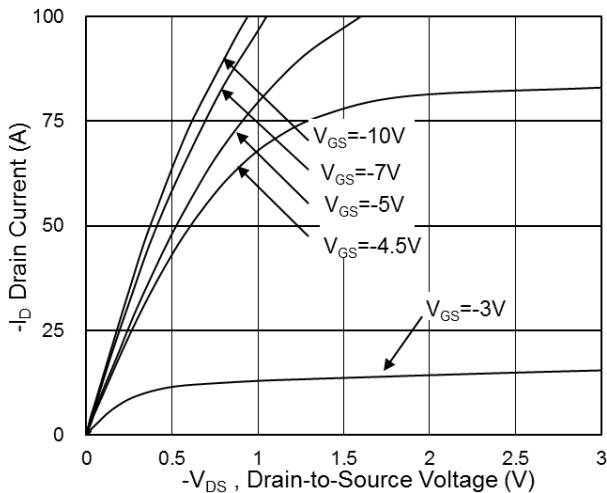


Fig.1 Typical Output Characteristics

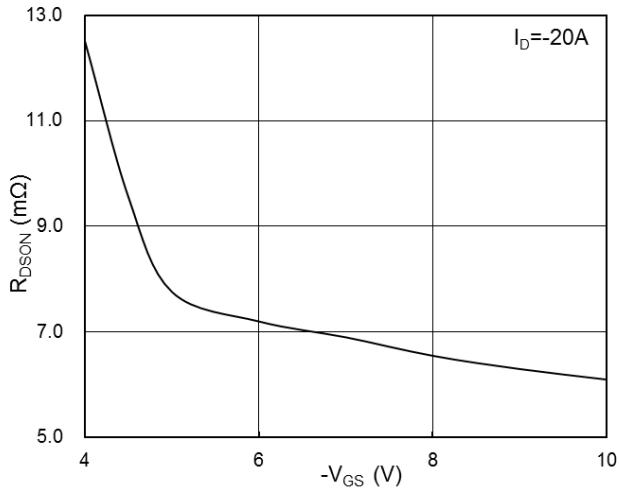


Fig.2 On-Resistance vs. Gate-Source Voltage

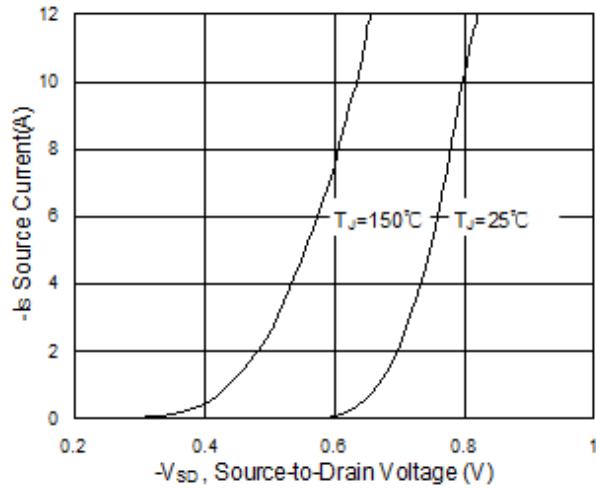


Fig.3 Forward Characteristics of Reverse

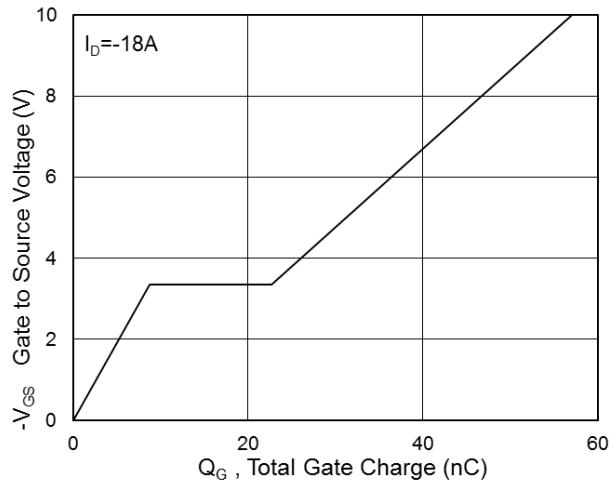


Fig.4 Gate-Charge Characteristics

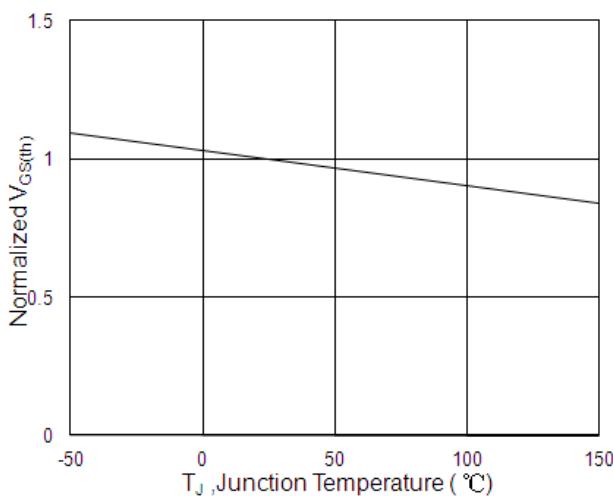


Fig.5 Normalized $-V_{GS(th)}$ vs. T_J

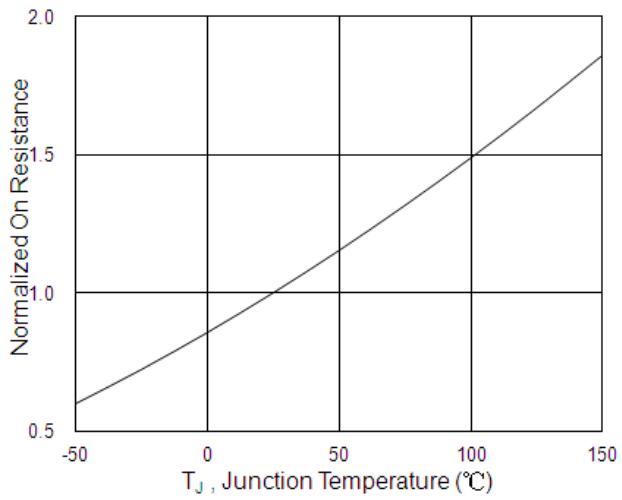
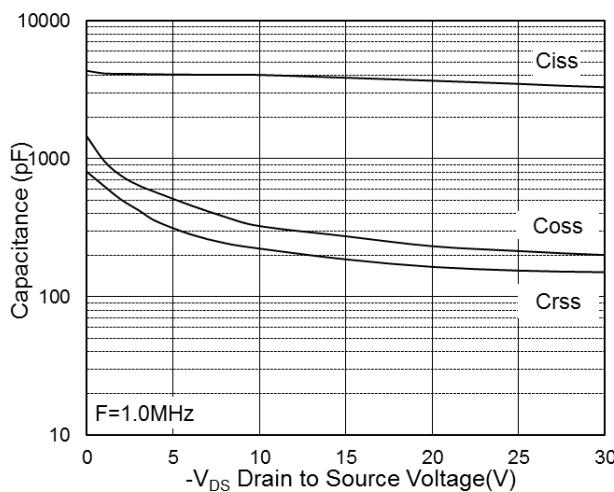
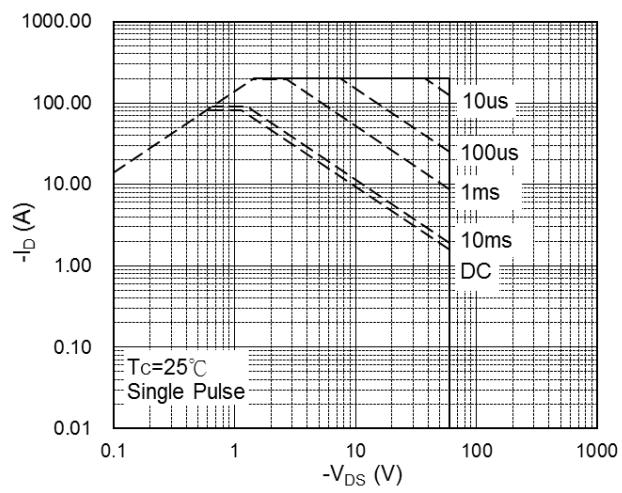
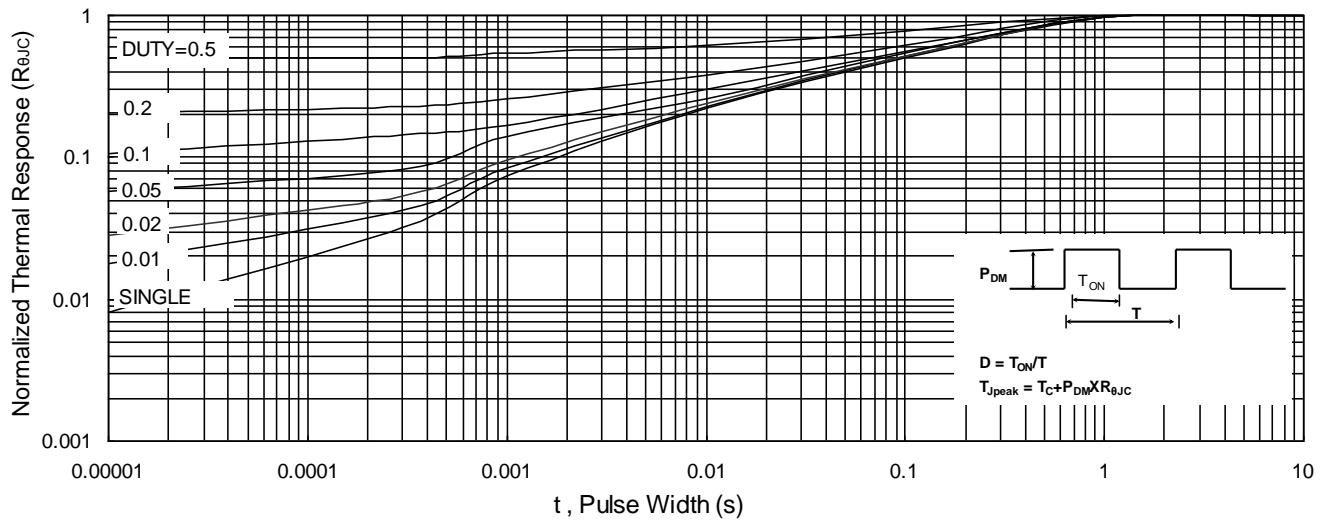
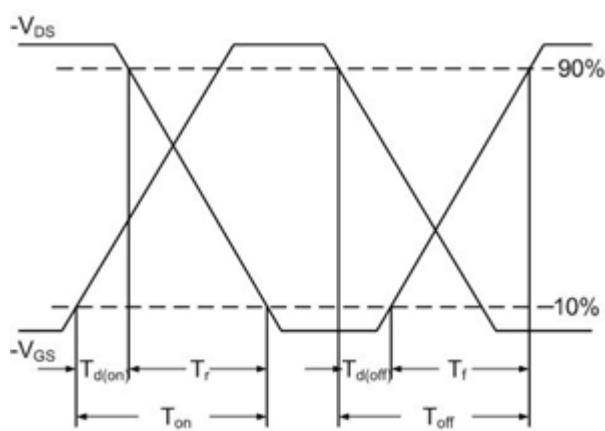
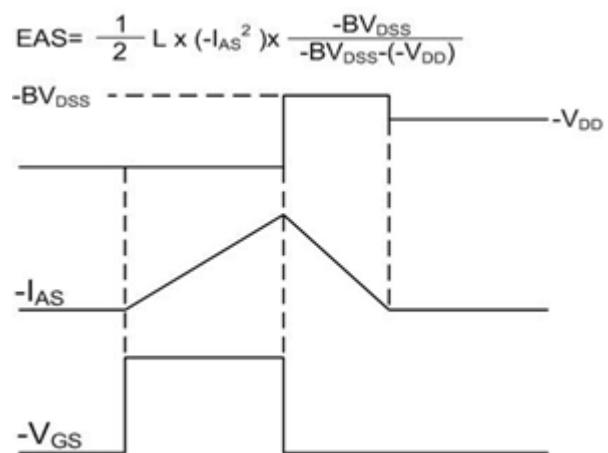
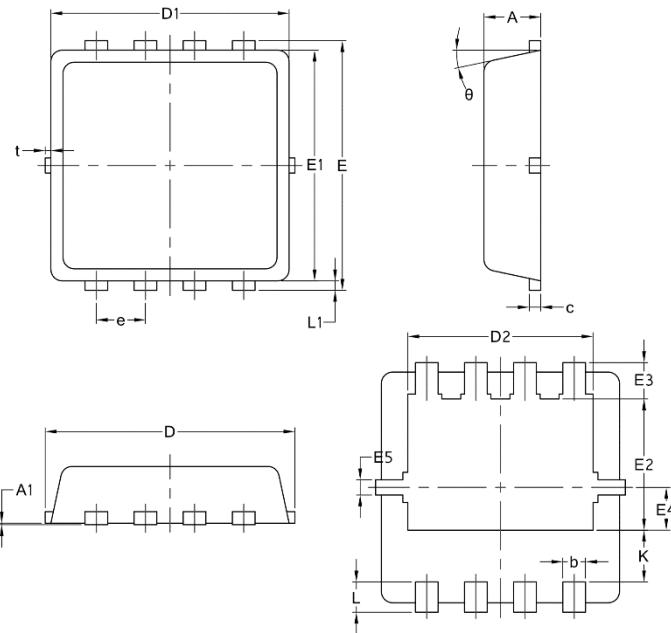


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

**Fig.7 Capacitance****Fig.8 Safe Operating Area****Fig.9 Normalized Maximum Transient Thermal Impedance****Fig.10 Switching Time Waveform****Fig.11 Unclamped Inductive Switching Waveform**

Package Mechanical Data-DFN3*3-8L-JQ Single


Symbol	Common		
	mm		
	Mim	Nom	Max
A	0.70	0.75	0.85
A1	/	/	0.05
b	0.20	0.30	0.40
c	0.10	0.152	0.25
D	3.15	3.30	3.45
D1	3.00	3.15	3.25
D2	2.29	2.45	2.65
E	3.15	3.30	3.45
E1	2.90	3.05	3.20
E2	1.54	1.74	1.94
E3	0.28	0.48	0.65
E4	0.37	0.57	0.77
E5	0.10	0.20	0.30
e	0.60	0.65	0.70
K	0.59	0.69	0.89
L	0.30	0.40	0.50
L1	0.06	0.125	0.20
t	0	0.075	0.13
Φ	10	12	14